	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
57	BRS	4	(releas$4 with mesh and (shav$4 or thin$ or reduc$ with thick$4) with (wafer or substrate or carrier)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/09/18 14:03				S73
58	BRS	115	releas$4 with mesh and (shav$4 or thin$ or reduc$ with thick$4) with (wafer or substrate or carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 04:15				S72
59	BRS	6	releas$4 near mesh and (shav$4 or thin$ or reduc$ with thick$4) with (wafer or substrate or carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/09/18 14:30				S74

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
60	BRS	61	releas$4 near (micro near machin$3 near mesh or grid or membrane) and (shav$4 or thin$ or reduc$ with thick$4) with (wafer or substrate or carrier) and mems	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 04:49				S75
61	BRS	9	("438"/$).ccls. and releas$4 near (micro near machin$3 near mesh or grid or membrane) and (shav$4 or thin$ or reduc$ with thick$4) with (wafer or substrate or carrier) and mems	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 04:46				S76

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
62	BRS	37	("438"/$).ccls. and releas$4 with (micro near machin$3 near mesh or grid or membrane) and (shav$4 or thin$ or reduc$ with thick$4) with (wafer or substrate or carrier) and mems	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 04:47				S79
63	BRS	4	("438"/$).ccls. and releas$4 with (micro near machin$3 near mesh or grid or membrane) and (shav$4 or thin$ or reduc$ with thick$4) near (wafer or substrate or carrier) and mems	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 04:47				S78

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
64	BRS	1	(releas$4 with (micro near machin$3 near mesh or grid or membrane) and (shav$4 or thin$ or reduc$ with thick$4) with (wafer or substrate or carrier) and mems).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 04:51				S80
65	BRS	22	(releas$4 with (micro near machin$3 near mesh or grid or membrane) and (shav$4 or thin$ or reduc$ with thick$4) with (wafer or substrate or carrier)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 04:51				S81
66	BRS	0	(438/459).ccls. and releas$4 with micro near machin$3 near mesh and mems	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 05:01				S82

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
67	BRS	1	("438"/$).ccls. and releas$4 with micro near machin$3 near mesh and mems	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 05:02				S83
68	BRS	57	("438"/$).ccls. and releas$4 with (micro near machin$3 near mesh or membrane) and mems	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 05:02				S84
69	BRS	16	("438"/$).ccls. and releas$4 near (micro near machin$3 near mesh or membrane) and mems	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 05:07				S85
70	BRS	0	("438"/$).ccls. and releas$4 near (micro near machin$3 near mesh or membrane) and mems and carrier with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 05:07				S86
71	BRS	3	releas$4 near (micro near machin$3 near mesh or membrane) and mems and carrier with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 05:08				S87

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
72	BRS	4	releas$4 near (micro near machin$3 near mesh or membrane) and mems and carrier with wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 05:08				S88

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	BRS	L7	0	("438"/977).ccls. and releas$4 with (micro near machin$3 near mesh or grid or membrane) and (shav$4 or thin$ or reduc$ with thick$4) with (wafer or substrate or carrier) and mems	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 09:10			
2	BRS	L1	3	("438"/455).ccls. and releas$4 with (micro near machin$3 near mesh or grid or membrane) and (shav$4 or thin$ or reduc$ with thick$4) with (wafer or substrate or carrier) and mems	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 09:10			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
3	BRS	L2	8	("438"/50).ccls . and releas$4 with (micro near machin$3 near mesh or grid or membrane) and (shav$4 or thin$ or reduc$ with thick$4) with (wafer or substrate or carrier) and mems	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 09:11			
4	BRS	L3	10	("438"/52).ccls . and releas$4 with (micro near machin$3 near mesh or grid or membrane) and (shav$4 or thin$ or reduc$ with thick$4) with (wafer or substrate or carrier) and mems	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 09:17			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
5	BRS	L4	6	("438"/53).ccls. and releas$4 with (micro near machin$3 near mesh or grid or membrane) and (shav$4 or thin$ or reduc$ with thick$4) with (wafer or substrate or carrier) and mems	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 09:19			
6	BRS	L5	2	("438"/48).ccls. and releas$4 with (micro near machin$3 near mesh or grid or membrane) and (shav$4 or thin$ or reduc$ with thick$4) with (wafer or substrate or carrier) and mems	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 09:20			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
7	BRS	L6	1	("438"/464).ccls. and releas$4 with (micro near machin$3 near mesh or grid or membrane) and (shav$4 or thin$ or reduc$ with thick$4) with (wafer or substrate or carrier) and mems	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/31 09:20			